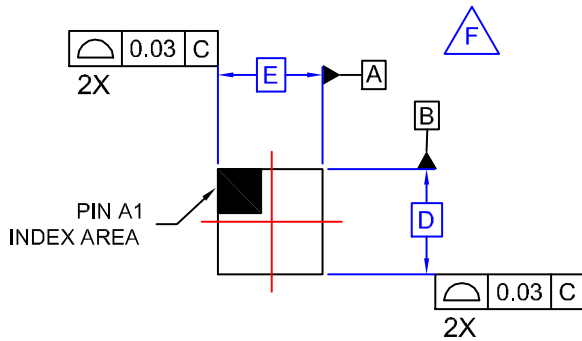
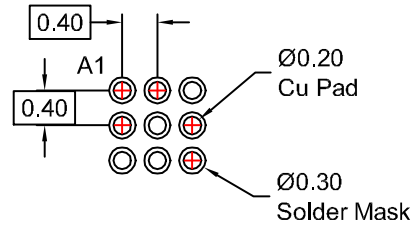


**WLCSP9 1.16x1.16x0.586**  
CASE 567RW  
ISSUE O

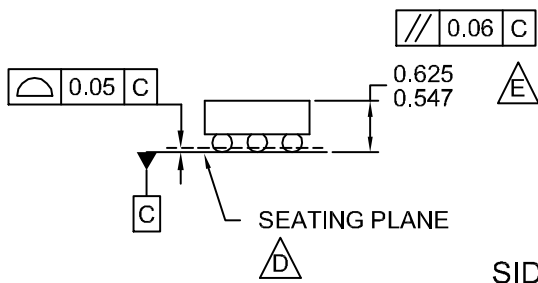
DATE 30 NOV 2016



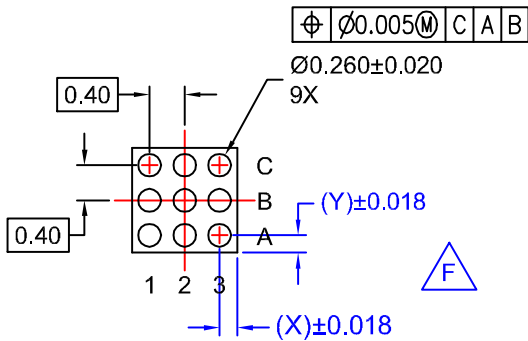
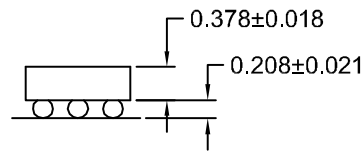
TOP VIEW



LAND PATTERN RECOMMENDATION  
(NSMD PAD TYPE)






SIDE VIEWS




BOTTOM VIEW

**NOTES:**

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASMEY14.5M, 1994.
-  D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
-  E. PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).
-  F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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<b>DESCRIPTION:</b>	<b>WLCSP9 1.16x1.16x0.586</b>	<b>PAGE 1 OF 1</b>

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